

-	346	carrier and substrate and posit\$3 near pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:32
-	301	carrier and posit\$3 near pin and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:40
-	2	("3973888" "4954308").PN.	USPAT	2004/07/01 16:37
-	6	("4332537" "4368168" "4442056" "4480975" "4741507" "4746392").PN.	USPAT	2004/07/01 16:39
-	43	carrier and posit\$3 near pin and angle near obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:44
-	1	2003-557561.NRAN.	DERWENT	2004/07/01 16:42
-	0	carrier and posit\$3 near pin near obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:44
-	48	carrier and posit\$3 near pin and obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:46
-	25	carrier and posit\$3 near pin and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:48
-	14	carrier and posit\$3 adj pins and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:49
-	147	carrier and posit\$3 adj pins and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:55
-	0	carrier and posit\$3 adj pins near obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:55

-	0	posit\$3 adj pins near obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:55
-	337	posit\$3 adj pins and obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:56
-	337	posit\$3 adj pins and obtuse	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 08:53
-	13	posit\$3 adj pins and obtuse and carrier and holder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/01 16:56

	Title	Current OR
1	Method and apparatus for the transport and tracking of an electronic component	439/73
2	Integrated ball grid array-pin grid array-flex laminate test assembly	439/77
3	Surface mount power supply device	361/760
4	Space-saving assemblies for connecting integrated circuits to circuit boards	361/767
5	Space-saving assemblies for connecting integrated circuits to circuit boards	361/784

	Title	Current OR
6	Multi-level assemblies for interconnecting integrated circuits	361/784
7	Multi-level assemblies and methods for interconnecting integrated circuits	361/784
8	Adaptor assembly for adding functionality to a pin grid receptacle on a circuit board	361/784

	Title	Current OR
15	I/O pin and method for making same	29/843
16	Connector and circuit package apparatus for pin array circuit module and circuit board	361/791
17	Chip carrier	361/708
18	Chip carrier	174/52.4
19	Process for manufacturing plastic pin grid arrays and the product produced thereby	29/827
20	Surface mountable integrated circuit package equipped with sockets	361/737
21	Decoupling capacitor for surface mounted leadless chip carrier, surface mounted leaded chip carrier and pin grid array package	361/306.2